ABSTRACT

A transponder contains an integrated circuit, a power transmitting component (antenna) and a capsule made of a thermoplastic resin (hot glue) that surrounds the circuit continuously at least on one surface of the circuit. The glue preferably is a polyamide and surrounds the circuit protectively, ensuring a mechanical connection between the circuit and the antenna. The encapsulation with the hot glue is conducted at pressures and temperatures that are below the pressures and temperatures encountered during conventional injection molding. The transponder can be integrated into an injection molded part, for example a coin, by being placed in an injection mold in which it is supported by feet and then surrounded by molding material in a conventional injection molding process so that it develops a more resistant sheath.